

## **AMENDMENTS TO THE SPECIFICATION:**

Please replace the paragraph beginning on page 5, line 9 of the Substitute Specification with the following amended paragraph:

According to the present invention, the micromechanical switch also has, for example, a bonding frame 8 and a first bonding pad 5, ~~i.e., a first terminal surface 5,~~ as well as a first conductor path 6 for contacting first bonding pad 5 to the suspension of contact element 3. In addition, the micromechanical switch according to the present invention also has a second bonding pad 5a and also a second conductor path 6a which is used for contacting second bonding pad 5a to the suspensions of first spring element 2. Moreover, the micromechanical switch also has a third bonding pad 5b and a third conductor path 6b which is used for contacting third bonding pad 5b with the suspension of an additional contact element 3b. Additional contact element 3b and its contacting devices (third bonding pad 5b and third conductor path 6b) are optional. What is essential for the operation of the micromechanical switch according to the present invention as a switch is that, via at least two bonding pads 5, 5a, and 5b and corresponding conductor paths 6, 6a, and 6b, at least two contacts are available which are in low-resistance contact with one another electrically during a corresponding movement of mass 1 such that first spring element 2 is displaced beyond the specified degree of displacement. For this purpose, the present invention may provide either that contact making between contact element 3, mass 1 and first spring element 2 and its suspension is effected toward second bonding pad 5a, or that contact making is effected from contact element 3 to further contact element 3b as well as to third conductor path 6b and third bonding pad 5b via mass 1, or even that two switches are implemented at the same time, both first contact element 3 and additional contact element 3b being provided and seismic mass 1 being electrically connected via second bonding pad 5a and second conductor path 6a.

Please replace the paragraph beginning on page 8, line 1 of the Substitute Specification with the following amended paragraph:

Figure 2 shows a sectional view of the micromechanical switch according to the present invention taken along section line AA of Figure 1. The view in Figure 1 is slightly enlarged and is somewhat distorted (in terms of proportions) compared with the view in Figure 1. Figure 2, like Figure 1, shows mass 1 and first spring element 2. Third spring element 4 is shown in Figure 2 on the side of first spring element 2 opposite mass 1. Figure 2 also shows suspension 2a of first spring element 2, the suspension being electrically connected to second bonding pad 5a by second conductor path 6a. Also visible in Figure 2 is frame 8 of the micromechanical switch. The entire micromechanical switch is provided on a substrate 10, according to the present invention, and the moving parts of the micromechanical switch, i.e., in particular mass 1 and

spring elements 2, 30, 3, 4 are covered by a cover 9. Cover 9 is not shown in Figure 1.

According to the present invention, substrate 10 is provided, in particular, in the form of a semiconductor substrate such as a silicon substrate, for example. The moving elements in the operating layer of the micromechanical switch designated in Figure 2 by reference numeral 11 are likewise provided according to the present invention in semiconductor material, in particular, such as in silicon, for example. According to the present invention, however, other materials may also be provided. Of course it is helpful, according to the present invention, to ensure good conductivity of the material of mass 1 and first spring element 2 or second spring element 30 or in general of all elements that are used to conduct current during contact making of the switch.